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**INFORMATION DISCLOSURE
 STATEMENT BY APPLICANT**
 Form PTO-1449 (Modified)
 (Use several sheets if necessary)

Sheet **1** of **1**

COMPLETELY KNOWN

Application Number	09/018,783
Confirmation Number	1242
Filing Date	February 4, 1998
First Named Inventor	Thomas L. Ritzdorf
Group Art Unit	2823
Examiner Name	Deven M. Collins
Attorney Docket No.	291958182US

U.S. PATENT DOCUMENTS

Examiner Initials	Cite No.	U.S. Patent or Application		Name of Patentee or Inventor of Cited Document	Date of Publication or Filing Date of Cited Document	Pages, Columns, Lines, Where Relevant Figures Appear
		NUMBER	Kind Code (if known)			
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Examiner Initials	Cite No.	Foreign Patent or Application		Name of Patentee or Applicant of Cited Document	Date of Publication or Filing Date of Cited Document	Pages, Columns, Lines, Where Relevant Figures Appear	T
		Office	NUMBER				

OTHER PRIOR ART-NON PATENT LITERATURE DOCUMENTS

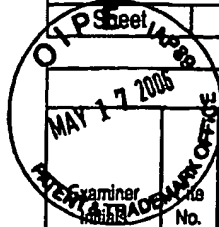
Examiner Initials	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume issue number(s), publisher, city and/or country where published.	T
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EXAMINER ON	DATE CONSIDERED 7/17/06
<p>*EXAMINER: Initial if reference considered, whether or not criteria is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant(s).</p>	

**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**Form PTO-1449 (Modified)
(Use several sheets if necessary)**COMPLETE IF KNOWN**

Application Number	09/018,783
Confirmation Number	1242
Filing Date	February 4, 1998
First Named Inventor	Thomas L. Ritzdorf
Group Art Unit	2811
Examiner Name	Thomas J. Magee
Attorney Docket No.	29195-8162US

Sheet 1 of 1

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		Office	NUMBER	Kind Code (if known)				

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ON

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Substitute for form 1449A/B/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use as many sheets as necessary)				Complete if Known	
				Application Number	09/018,783-Conf. #1242
				Filing Date	February 4, 1998
				First Named Inventor	Thomas L. Ritzdorf
				Art Unit	2811
				Examiner Name	O. Nadav
Sheet	1	of	1	Attorney Docket Number	291958162US

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Examiner Initials*	Cite No. ¹	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number-Kind Code ² (if known)			
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NON PATENT LITERATURE DOCUMENTS			
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Examiner Signature	ON	Date Considered	7/17/06
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